



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

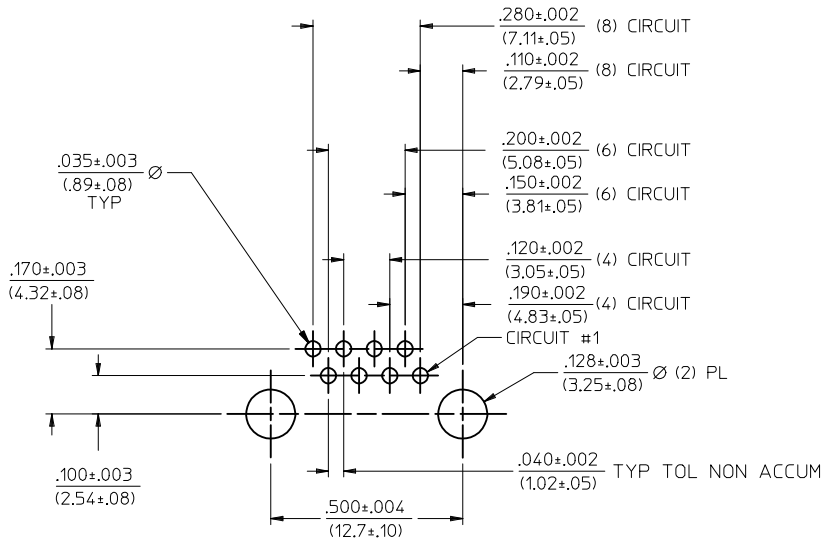
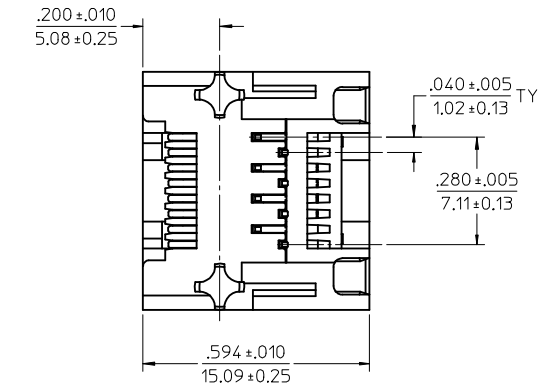
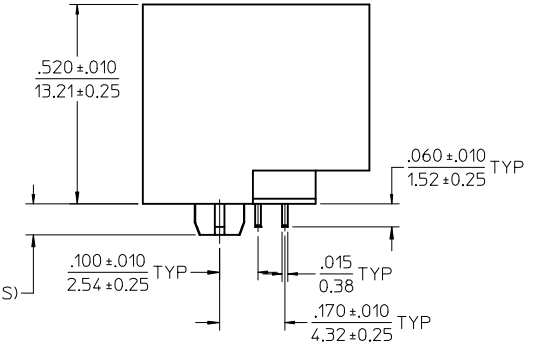
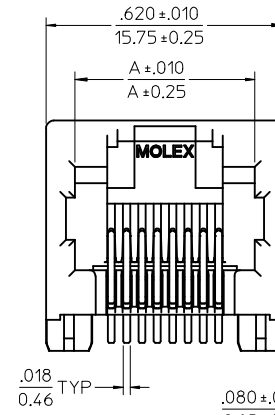
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NOTES

- 1) MATERIAL:
HOUSING: GLASS FILLED NYLON, 94V-0 COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THICK
SHIELD: BRASS
- 2) PLATING:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
- 3) PRODUCT SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
- 4) PACKAGING OPTIONS:
CONNECTOR ASSEMBLIES IN EXTRUDED TUBES
PER PACKAGING SPECIFICATION PK-43860-004
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR
REFERENCE ONLY
- 6) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PC BOARD THICKNESS .039/1.00

MATERIAL NUMBER	CONNECTOR SIZE	DIM. "A"	CIRCUITS
44380-0001	8	.470/11.94	8
44380-0002	6	.389/9.88	6
44380-0003	6	.389/9.88	4
44380-0019	8	.470/11.94	4

REV	DESCRIPTION	DATE	BY	CHKD	APPR
01	UPDATE VIEWS	2015/05/19	UCP	UCP	UCP
02	EC NO: UCP2015-0148	2014/07/16	DRW	DRW	DRW
		2014/07/16	NGUYEN	JBELL	FSMITH

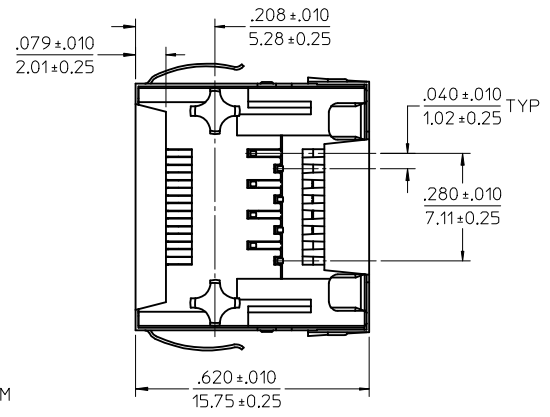
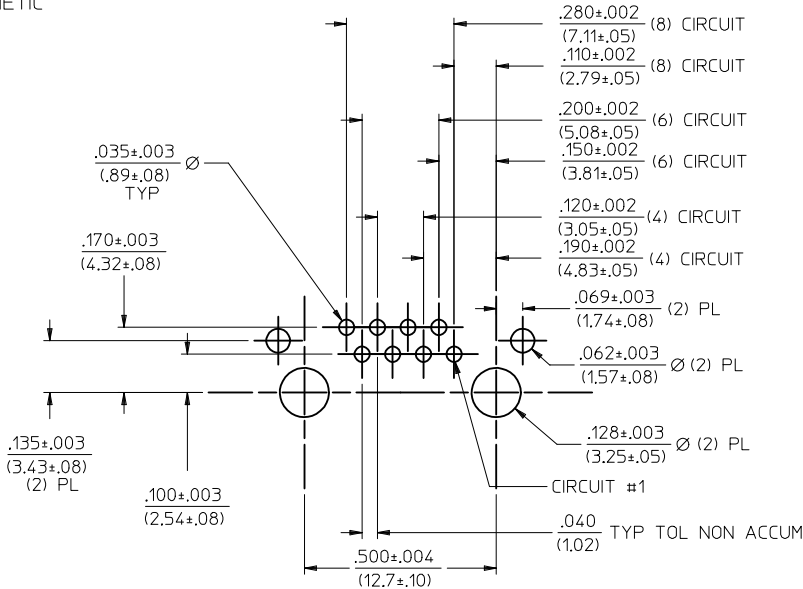
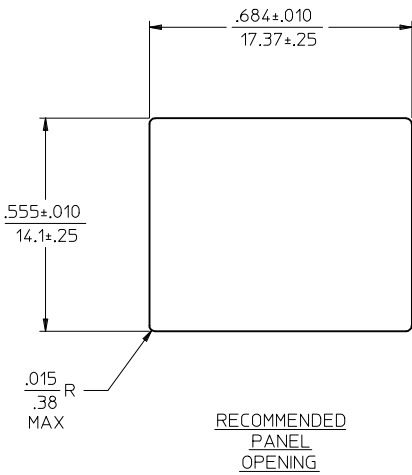
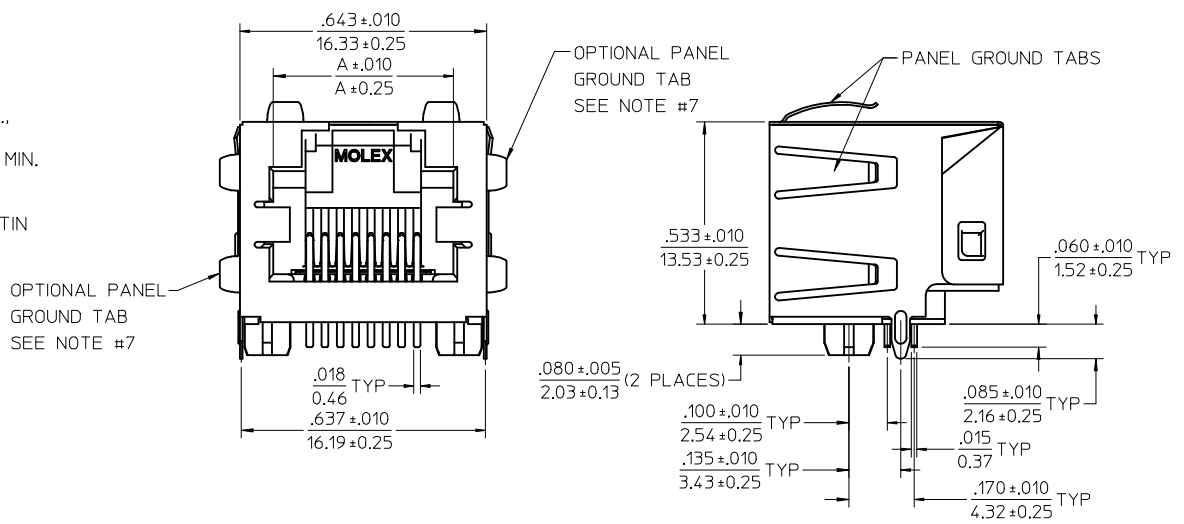
QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)
▽=0	mm
▽=0	INCH
▽=0	ANGULAR ±1/2°

DIMENSION STYLE		SCALE		DESIGN UNITS	
IN/MM		4:1		INCH	
DRAWN BY	DATE	TITLE			
MAYO	1999/04/09	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)			
CHECKED BY	DATE				
ROBERTS	1999/04/09				
APPROVED BY	DATE	DOCUMENT NO.			
ROBERTS	1999/04/09	SD-44380-001			

THIRD ANGLE PROJECTION		SHEET NO.	
		1 OF 5	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

NOTES

- 1) MATERIAL:
HOUSING: GLASS FILLED NYLON, 94V-0 COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THICK
SHIELD: BRASS
- 2) PLATING:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
SHIELD:
100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES
(1.27 MICROMETERS) COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN
- 3) PRODUCT SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
- 4) PACKAGING OPTIONS:
CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS
PER PACKAGING SPECIFICATION PK-44380-005
OPTION (44380-2004) PACKAGED IN TAPE AND REEL
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY
- 6) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS
- 7) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
- 8) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

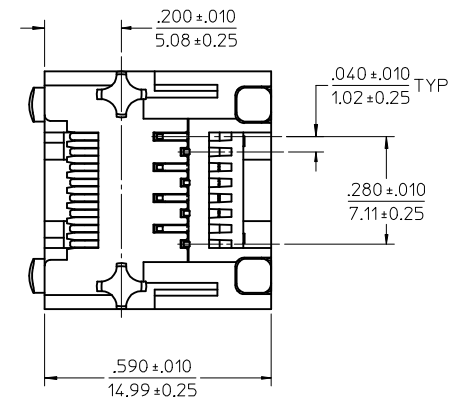
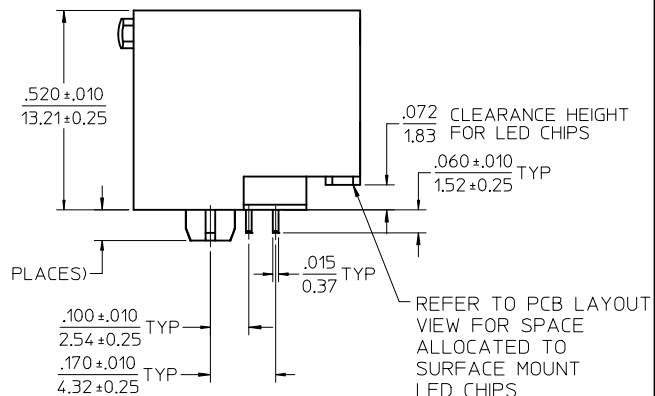
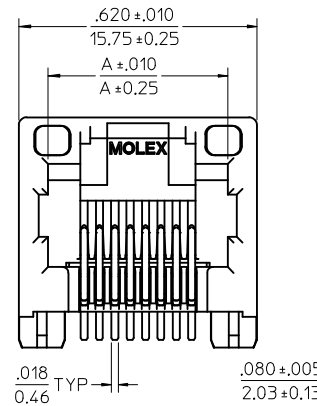


PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PC BOARD THICKNESS: .039/1.00

MATERIAL NUMBER	CONNECTOR SIZE	DIM. "A"	CIRCUITS	PANEL GROUND TABS
44380-0004	8	.470/11.94	8	ALL
44380-0005	6	.389/9.88	6	ALL
44380-0006	6	.389/9.88	4	ALL
44380-0013	8	.470/11.94	8	SEE NOTE #7
44380-0014	6	.389/9.88	6	SEE NOTE #7
44380-0015	6	.389/9.88	4	SEE NOTE #7
44380-2004	8	.470/11.94	8	ALL

SEE SHEET 1 EC NO: UCP2015-0148 DRAWING NO: 2014/07/16 CHKD: J.BELL APPR: F.S.MITH DESCRIPTION: 2015/05/19	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± --- 0 PLACE ± --- ± ---	mm INCH	DRAWN BY MAYO	DATE 1999/04/09	TITLE INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)			
ANGULAR ±1/2°		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-44380-001		SHEET NO. 2 OF 5		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

- NOTES
- MATERIAL:
HOUSING:
GLASS FILLED NYLON, 94V-0, COLOR: BLACK
TERMINALS:
PHOSPHOR BRONZE, .015/(0.38) THK
LIGHTPIPE:
POLYCARBONATE- WAVE OR HAND SOLDER ONLY
(NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW
SOLDER PROCESSES)
POLYSULFONE - MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
 - PLATING:
TERMINAL:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
 - PACKAGING SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
 - PACKAGING:
PER PACKAGING SPECIFICATION PK-43860-004
 - APPLICATION SPECIFICATION: AS-43860-001.
 - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.
 - REFER TO PAGE (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



MATERIAL NUMBER	LIGHTPIPE MATERIAL	CONNECTOR SIZE	DIM. "A"	CIRCUITS
44380-0007	POLYCARBONATE	8	.470/11.94	8
44380-0008	POLYCARBONATE	6	.389/9.88	6
44380-0009	POLYCARBONATE	6	.389/9.88	4
44380-0020	POLYSULFONE	8	.470/11.94	8
44380-0021	POLYSULFONE	6	.389/9.88	6
44380-0022	POLYSULFONE	6	.389/9.88	4

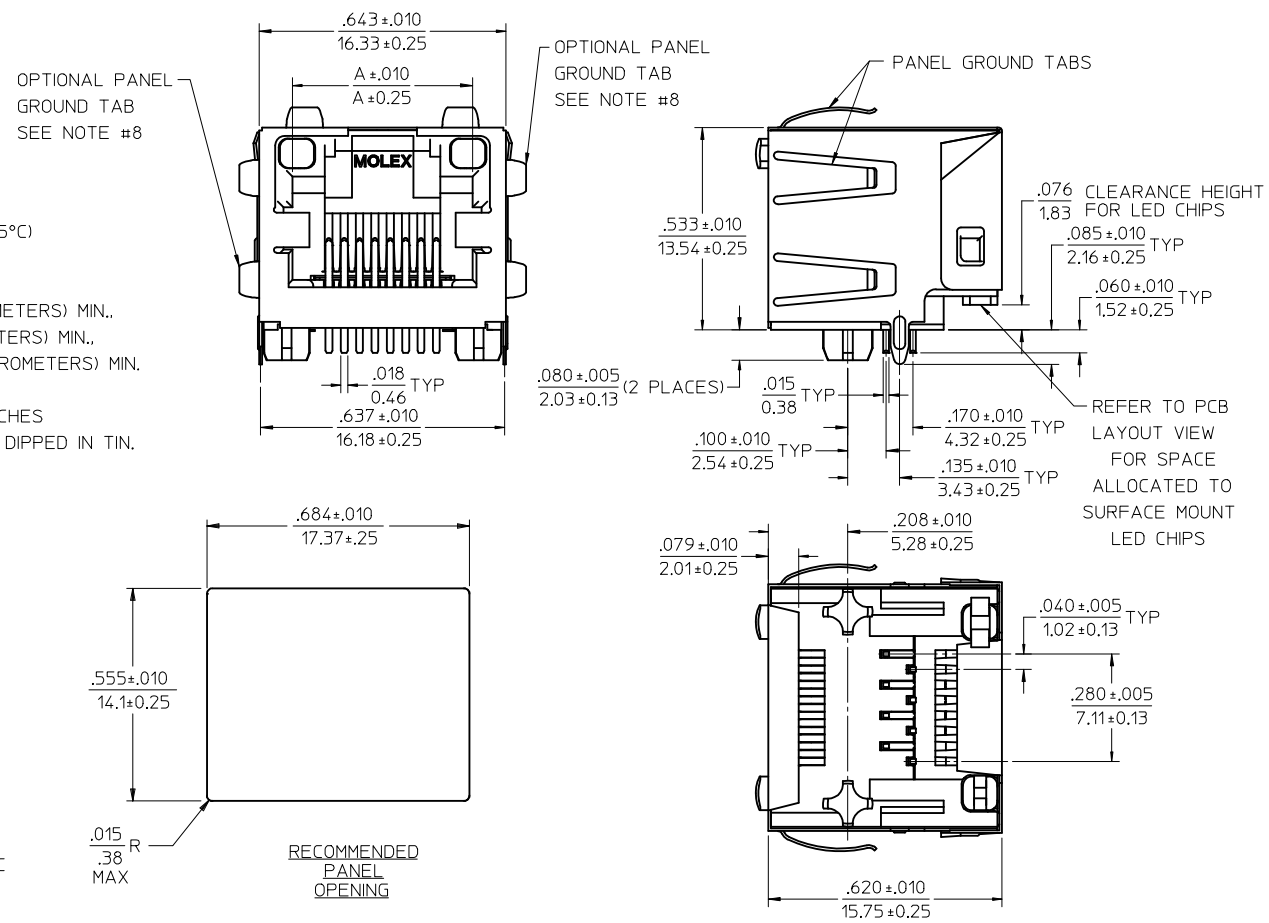
SEE SHEET 1 EC NO: UCP2015-0148 DRAWN: NGUYEN 2014/07/16 CHKD: BELL 2014/07/16 APPR: F. SMITH 2015/05/19	QUALITY SYMBOLS	DESCRIPTION
	$\nabla=0$ $\nabla=0$ $\nabla=0$	
C2	REV	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES ±	±
3 PLACES ±	±
2 PLACES ±	±
1 PLACE ±	±
0 PLACE ±	±
ANGULAR ±1/2°	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
IN/MM		4:1	INCH	
DRAWN BY	DATE	TITLE		
MAYO	1999/04/09	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)		
CHECKED BY	DATE	molex		
ROBERTS	1999/04/09	SD-44380-001		
APPROVED BY	DATE	SHEET NO.		
ROBERTS	1999/04/09	3 OF 5		
MATERIAL NO.		DOCUMENT NO.		
SEE CHART		SD-44380-001		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

NOTES

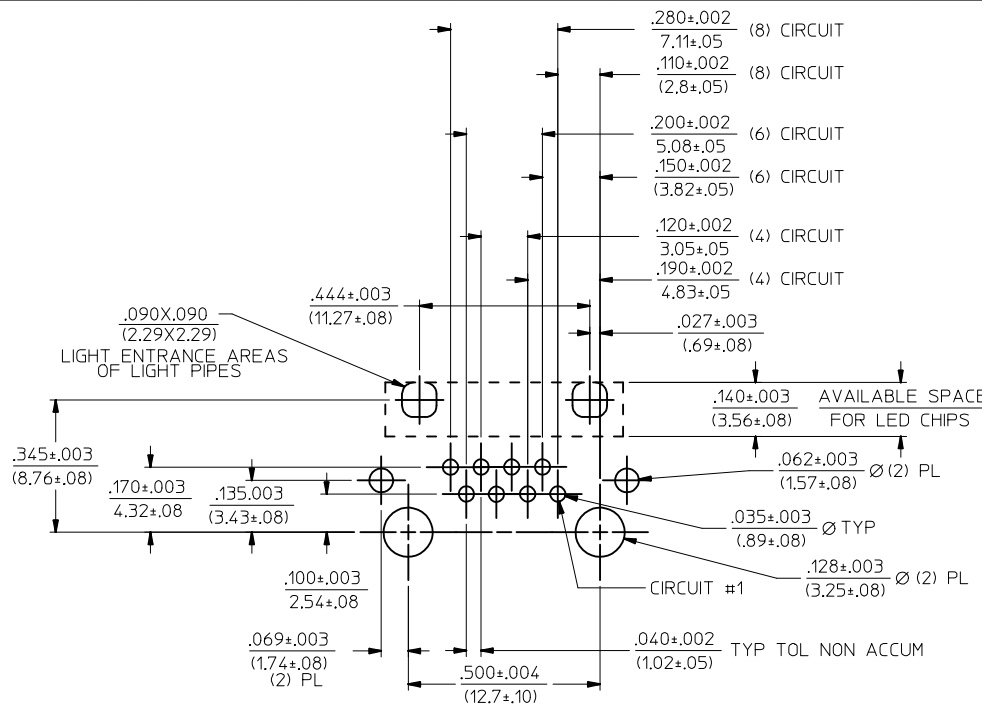
- 1) MATERIAL:
 - HOUSING: GLASS FILLED NYLON, 94V-0, COLOR: BLACK
 - TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THK
 - SHIELD: BRASS
 - LIGHTPIPE: POLYCARBONATE - WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)
 - POLYSULFONE - MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)
- 2) PLATING:
 - TERMINAL: SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN., SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN., WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
 - SHIELD: 100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES (1.27 MICROMETERS) COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN.
- 3) PRODUCT SPECIFICATION:
 - CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX PRODUCT SPECIFICATION PS-43860-003.
- 4) PACKAGING:
 - CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS PER PACKAGING SPECIFICATION PK-44380-005 .
- 5) APPLICATION SPECIFICATION: AS-43860-001.
- 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 7) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.
- 8) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
- 9) REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
- 10) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



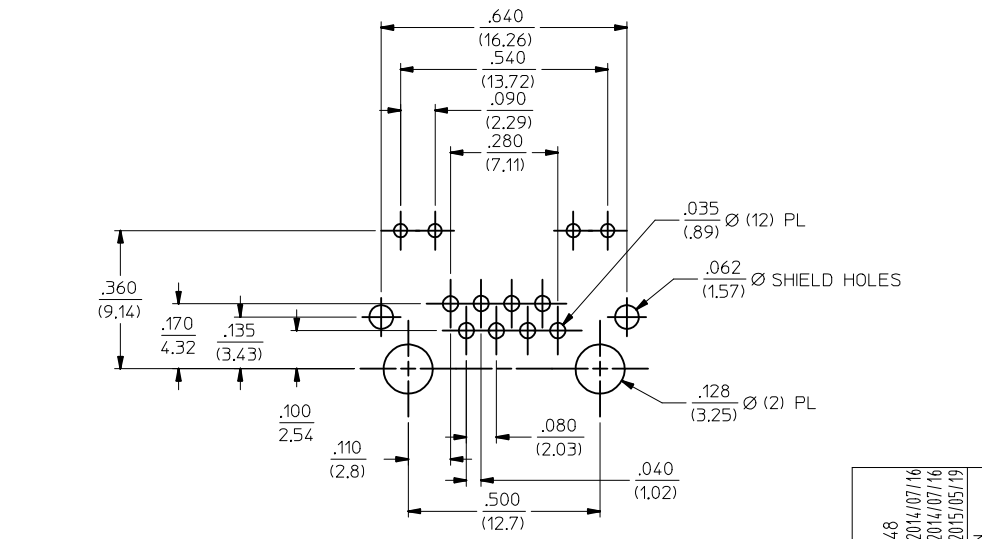
MATERIAL NUMBER	LIGHTPIPE MATERIAL	CONN SIZE	DIM. "A"	CIRCUITS	PANEL GROUND TABS
44380-0010	POLYCARBONATE	8	.470/11.94	8	ALL
44380-0011	POLYCARBONATE	6	.389/9.88	6	ALL
44380-0012	POLYCARBONATE	6	.389/9.88	4	ALL
44380-0016	POLYCARBONATE	8	.470/11.94	8	SEE NOTE #8
44380-0017	POLYCARBONATE	6	.389/9.88	6	SEE NOTE #8
44380-0018	POLYCARBONATE	6	.389/9.88	4	SEE NOTE #8
44380-1010	POLYSULFONE	8	.470/11.94	8	ALL
44380-1011	POLYSULFONE	6	.389/9.88	6	ALL
44380-1012	POLYSULFONE	6	.389/9.88	4	ALL
44380-1016	POLYSULFONE	8	.470/11.94	8	SEE NOTE #8
44380-1017	POLYSULFONE	6	.389/9.88	6	SEE NOTE #8
44380-1018	POLYSULFONE	6	.389/9.88	4	SEE NOTE #8

SEE SHEET 1
 EC NO: WGP2015-0148
 DRAWINGUYEN 2014/07/16
 CHKD:JBELL 2014/07/16
 APPR:FSMITH 2015/05/19

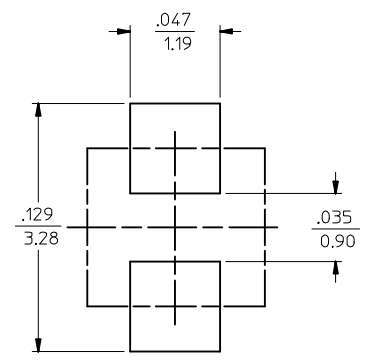
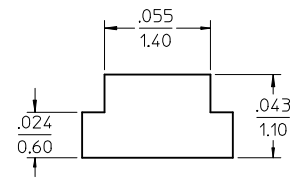
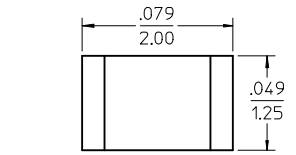
QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
▽=0	mm INCH	IN/MM	4:1	INCH	
▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT) molex DOCUMENT NO. SD-44380-001 SHEET NO. 4 OF 5		
▽=0	3 PLACES ± --- ± ---	MAYO 1999/04/09			
▽=0	2 PLACES ± --- ± ---	CHECKED BY DATE			
	1 PLACE ± --- ± ---	ROBERTS 1999/04/09			
	0 PLACE ± --- ± ---	APPROVED BY DATE			
	ANGULAR ±1/2°	ROBERTS 1999/04/09			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.			
		SEE CHART			
		SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



MOLEX RECOMMENDED
PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PC BOARD THICKNESS: .039/1.00



TYPICAL COMPETITION
PCB LAYOUT WITH
INTEGRAL LED'S
(SHOWN FOR REFERENCE ONLY)
RECOMMENDED PC BOARD THICKNESS: .039/1.00



RECOMMENDED SMT
LED DIMENSIONS
SCALE 20:1
(SEE NOTE 1)

RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 20:1
(SEE NOTE 1)

NOTES:
1. FOR CROSS REFERENCE OF RECOMMENDED LEDS SEE MOLEX WEB SITE.

SEE SHEET 1 EC NO: UCP2015-0148 DRAWN: NGUYEN 2014/07/16 CHKD: BELL 2014/07/16 APPR: F. SMITH 2015/05/19	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY MAYO	DATE 1999/04/09	TITLE INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)			
C2	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.	
		SEE CHART		SD-44380-001		SHEET NO. 5 OF 5		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	